Product Change Notification

Change Notification #:	**114273 - 00**
Change Title:	**Intel® SSD DC S3300 Series (300GB, 480GB, 800GB, 2.5in SATA 6Gb/s, 20nm, MLC) 7mm, Generic 50 Pack Intel® SSD DC S3300 Series (300GB, 480GB, 800GB, 2.5in SATA 6Gb/s, 20nm, MLC) 7mm, Generic Single Pack Intel® SSD DC S3500 Series (1.2TB, 1.6TB, 2.5in SATA 6Gb/s, 20nm, MLC) 7mm, Generic 50 Pack Intel® SSD DC S3500 Series (1.2TB, 1.6TB, 2.5in SATA 6Gb/s, 20nm, MLC) 7mm, Generic Single Pack, PCN 114273-00, Label, Australian Regulatory Label Update**
Date of Publication:	**December 22, 2015**

Key Characteristics of the Change:

Label

Forecasted Key Milestones:

Date Customer Must be Ready to Receive Post-Conversion Material*:	Jan 06, 2016

* Intel will attempt to deplete pre-conversion material before shipping post-conversion material but there is a possibility of Intel shipping mixed inventory. Therefore, customers will need to manage and migrate to the post-conversion material as soon as possible

Description of Change to the Customer:

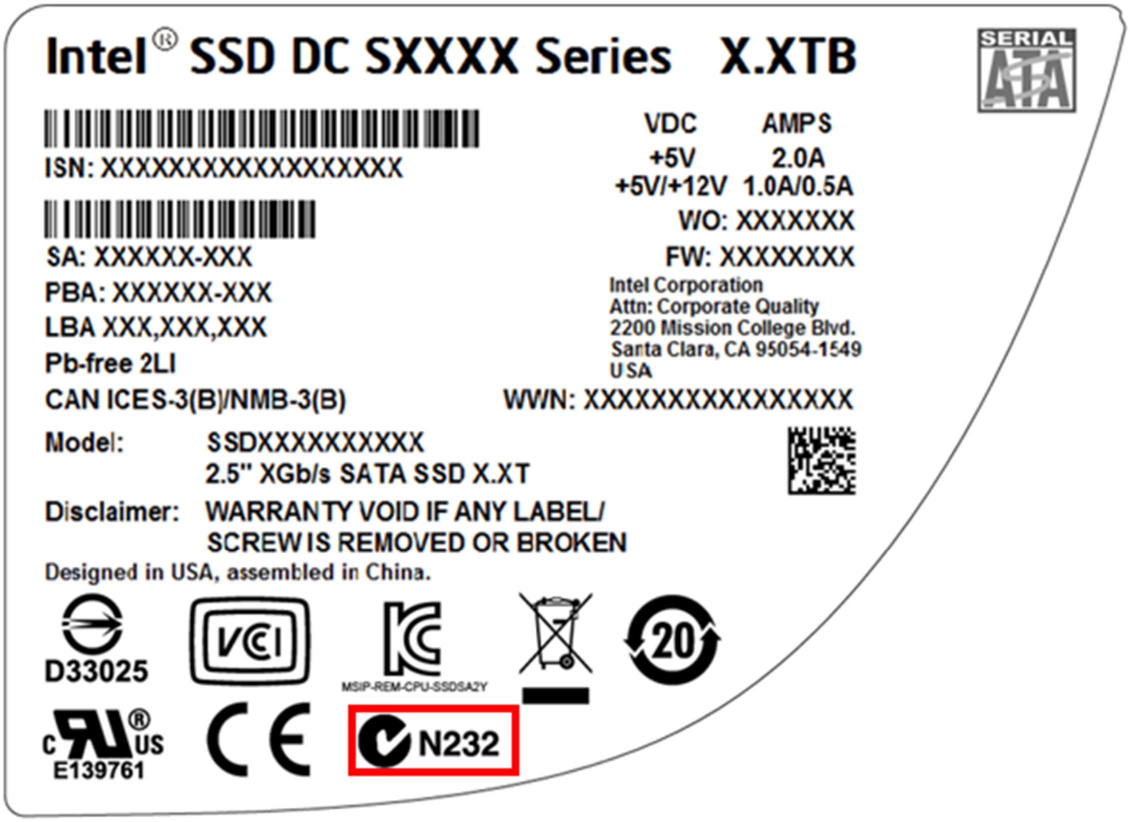
The following label changes supporting the Australia Regulatory Mark Change:

The Intel® SSD DC S3300 Series and Intel® SSD DC S3500 Series SKUs listed in the Products Affected table below will have the following Australia Regulatory Mark Change:
The Australian Communications and Media Authority's (ACMA) labeling arrangements to reflect

- Regulatory compliance changed on 1 March 2013, to be phased in over a three-year transition period. Products shipping March 1, 2016 need to be labeled with the "RCM" mark.
- Per ACMA requirements, Intel will be changing the C-Tick regulatory mark on all products to the "RCM" mark, and will implement the change no later than Mar 1st, 2016.

See the following labels for details:

Intel® SSD DC S3300/S3500Series - 2.5 in.
Current



Intel® SSD DC SXXXX Series X.XTB

SERIAL ATA

ISN: XXXXXXXXXXXXXXXXX

VDC	AMPS
+5V	2.0A
+5V/+12V	1.0A/0.5A

WO: XXXXXXX
FW: XXXXXXXX

SA: XXXXXX-XXX
PBA: XXXXXX-XXX
LBA XXX,XXX,XXX
Pb-free 2LI
CAN ICES-3(B)/NMB-3(B)

Intel Corporation
Attn: Corporate Quality
2200 Mission College Blvd.
Santa Clara, CA 95054-1549
USA

WWN: XXXXXXXXXXXXXXXX

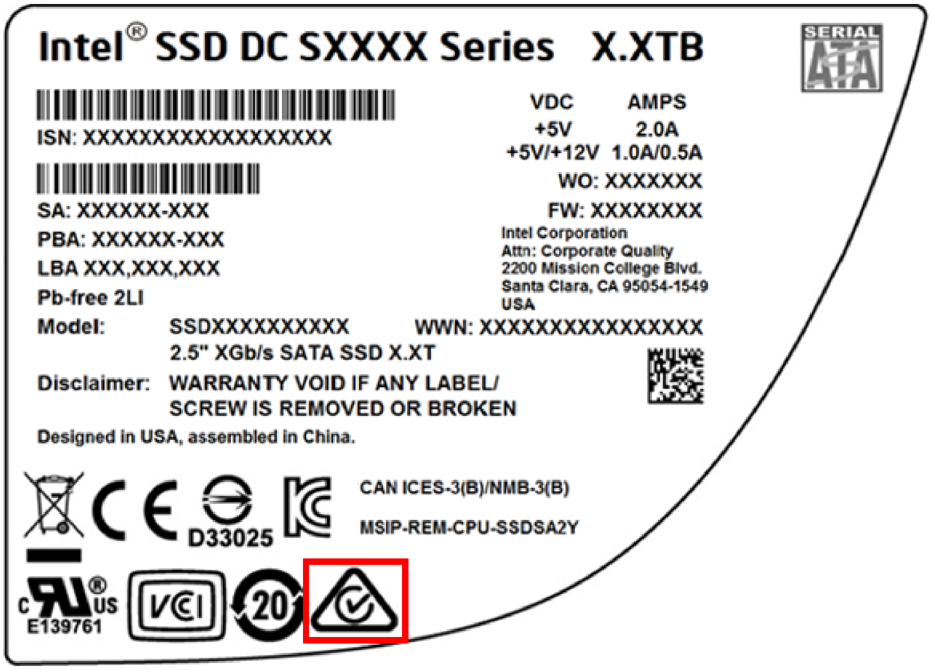
Model: SSDXXXXXXXXXX
2.5" XGb/s SATA SSD X.XT

Disclaimer: WARRANTY VOID IF ANY LABEL/
SCREW IS REMOVED OR BROKEN

Designed in USA, assembled in China.

D33025
MSIP-REM-CPU-SSDSA2Y
20
E139761
N232

New



Intel® SSD DC SXXXX Series X.XTB

SERIAL ATA

ISN: XXXXXXXXXXXXXXXXX

VDC	AMPS
+5V	2.0A
+5V/+12V	1.0A/0.5A

WO: XXXXXXX
FW: XXXXXXXX

SA: XXXXXX-XXX
PBA: XXXXXX-XXX
LBA XXX,XXX,XXX
Pb-free 2LI

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Model: SSDXXXXXXXXXX
2.5" XGb/s SATA SSD X.XT

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Designed in USA, assembled in China.

D33025
CAN ICES-3(B)/NMB-3(B)
MSIP-REM-CPU-SSDSA2Y
E139761
20

Customer Impact of Change and Recommended Action:

There is no change to the Form, Fit, or Function of the product. The change is only to the labels used on the product.

Customers should be aware of the changes to the label and take appropriate actions to accommodate the changes and avoid impact to their process.

Milestone dates are estimates and subject to change based on business and operational conditions.

Please contact your local Intel Field Sales Rep if you have any further questions about these changes.

* Other names and brands may be claimed as the property of others.

Products Affected / Intel Ordering Codes:

Product Code	MM#
SSDSC2BB016T4	929754
SSDSC2BB016T401	929756
SSDSCKHB080G4	932261
SSDSCKHB120G4	932262
SSDSCKHB340G4	932263
SSDSCKHB080G401	932264
SSDSCKHB120G401	932265
SSDSCKHB340G401	932266
SSDSC2BB012T401	932567
SSDSC2BB012T4	932568
SSDSC2BB300H401	933246
SSDSC2BB480H401	933247
SSDSC2BB800H401	933248
SSDSC2BB300H4	933249
SSDSC2BB480H4	933250
SSDSC2BB800H4	933252

PCN Revision History:

Date of Revision:	Revision Number:	Reason:
December 22, 2015	00	Originally Published PCN

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114273 - 00

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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

Americas Contact: asmo.pcn@intel.com
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